Abstract

A composition suitable for eliminating a thermosetting resin (and a method of so using the composition) is disclosed. In the composition, tetra methyl ammonium hydroxide (TMAH) is included so as to eliminate the thermosetting resin. Accordingly, the composition is suitable for removing a dielectric layer, an organic protective layer, an insulating layer, an alignment layer, black matrices and color filters, etc. made form a thermosetting resin in an LCD or a semiconductor, and permits a reproduction or a rework of the thermosetting resin film.